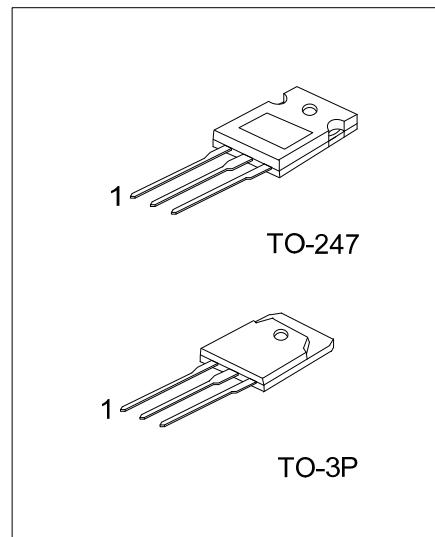


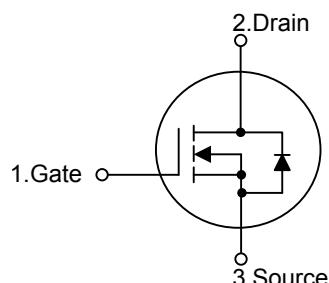
**10N90****Power MOSFET****10A, 900V N-CHANNEL  
POWER MOSFET****■ DESCRIPTION**

The UTC **10N90** is a N-channel mode power MOSFET using UTC's advanced technology to provide customers with planar stripe and DMOS technology. This technology allows a minimum on-state resistance and superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

The UTC **10N90** is generally applied in high efficiency switch mode power supply.

**■ FEATURES**

- \*  $R_{DS(ON)} = 1.35\Omega$  @  $V_{GS} = 10V$
- \* Lower Leakage Current:  $25\mu A$  (Max.) @  $V_{DS} = 900V$
- \* Improved Gate Charge

**■ SYMBOL****■ ORDERING INFORMATION**

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
10N90L-T3P-T	10N90G-T3P-T	TO-3P	G	D	S	Tube
10N90L-T47-T	10N90G-T47-T	TO-247	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

10N90L-T3P-T	(1) Packing Type (2) Package Type (3) Lead Free	(1) T: Tube (2) T3P:TO-3P, T47: TO-247 (3) G: Halogen Free, L: Lead Free
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■ ABSOLUTE MAXIMUM RATINGS ( $T_c=25^\circ\text{C}$ , unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	900	V
Gate-Source Voltage		$V_{GSS}$	$\pm 30$	V
Drain Current	Continuous	$I_D$	10	A
	Pulsed (Note 2)	$I_{DM}$	40	A
Avalanche Current (Note 2)		$I_{AR}$	10	A
Avalanche Energy	Single Pulsed (Note 3)	$E_{AS}$	794	mJ
	Repetitive (Note 2)	$E_{AR}$	28	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	1.5	V/ns
Power Dissipation		$P_D$	183	W
Junction Temperature		$T_J$	+150	$^\circ\text{C}$
Storage Temperature		$T_{STG}$	-55~+150	$^\circ\text{C}$

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2.  $L = 15\text{mH}$ ,  $I_{AS} = 10\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 27\Omega$ , Starting  $T_J = 25^\circ\text{C}$

3.  $I_{SD} \leq 10\text{A}$ ,  $di/dt \leq 190\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$

4. Pulse Test: Pulse width  $\leq 250\mu\text{s}$ , Duty cycle  $\leq 2\%$

## ■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient		$\theta_{JA}$	40	$^\circ\text{C}/\text{W}$
Junction to Case		$\theta_{JC}$	0.68	$^\circ\text{C}/\text{W}$

■ ELECTRICAL CHARACTERISTICS ( $T_c=25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=250\mu\text{A}$ , $V_{GS}=0\text{V}$	900			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D=250\mu\text{A}$		1.11		$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=900\text{V}$			25	$\mu\text{A}$
Gate- Source Leakage Current	Forward	$V_{GS}=+30\text{V}$			100	nA
	Reverse	$V_{GS}=-30\text{V}$			-100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	3.0		5.0	V
Static Drain-Source On-State Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}$ , $I_D=5\text{A}$		1.15	1.35	$\Omega$
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{ISS}$	$V_{GS}=0\text{V}$ , $V_{DS}=25\text{V}$ , $f=1.0\text{MHz}$		2760	3580	pF
Output Capacitance	$C_{OSS}$			245	290	pF
Reverse Transfer Capacitance	$C_{RSS}$			105	125	pF

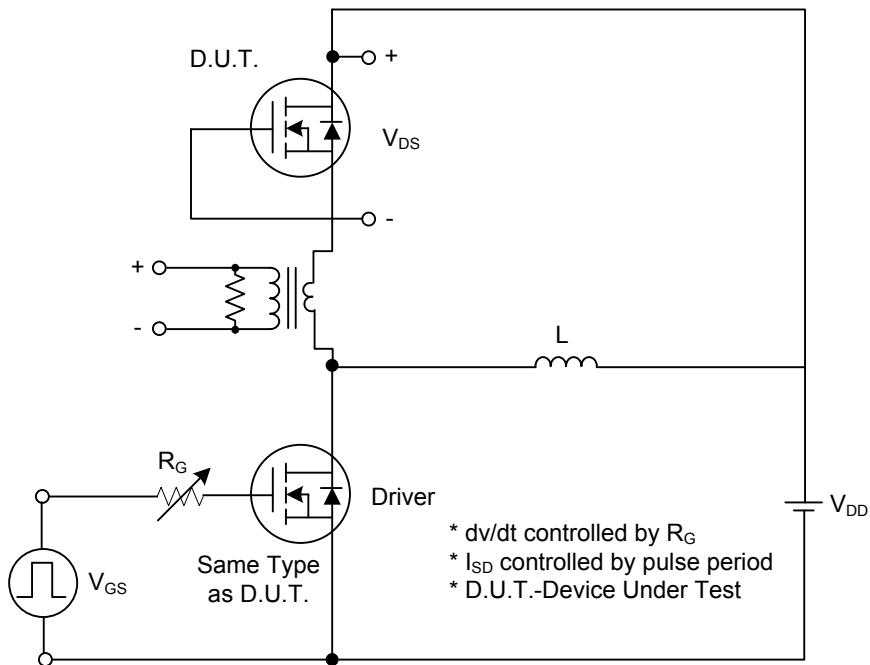
## ■ ELECTRICAL CHARACTERISTICS(Cont.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SWITCHING PARAMETERS</b>						
Total Gate Charge	$Q_G$	$V_{GS}=10V, V_{DS}=720V, I_D=10A$		127	165	nC
Gate to Source Charge	$Q_{GS}$	(Note 1, 2)		19.2		nC
Gate to Drain Charge	$Q_{GD}$			56.8		nC
Turn-ON Delay Time	$t_{D(ON)}$			29	70	ns
Rise Time	$t_R$	$V_{DD}=450V, I_D=10A, R_G=9.6\Omega$		54	20	ns
Turn-OFF Delay Time	$t_{D(OFF)}$	(Note 1, 2)		161	330	ns
Fall-Time	$t_F$			47	105	ns
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Maximum Body-Diode Continuous Current	$I_S$	Integral Reverse Pn-Diode In			10	A
Maximum Body-Diode Pulsed Current (Note1)	$I_{SM}$	The MOSFET			40	A
Drain-Source Diode Forward Voltage (Note 1)	$V_{SD}$	$I_S=10A, V_{GS}=0V, T_J=25^\circ C$			1.4	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F=10A, dI_F/dt=100A/\mu s,$		690		ns
Body Diode Reverse Recovery Charge	$Q_{RR}$	$T_J=25^\circ C$ (Note 1)		11.94		$\mu C$

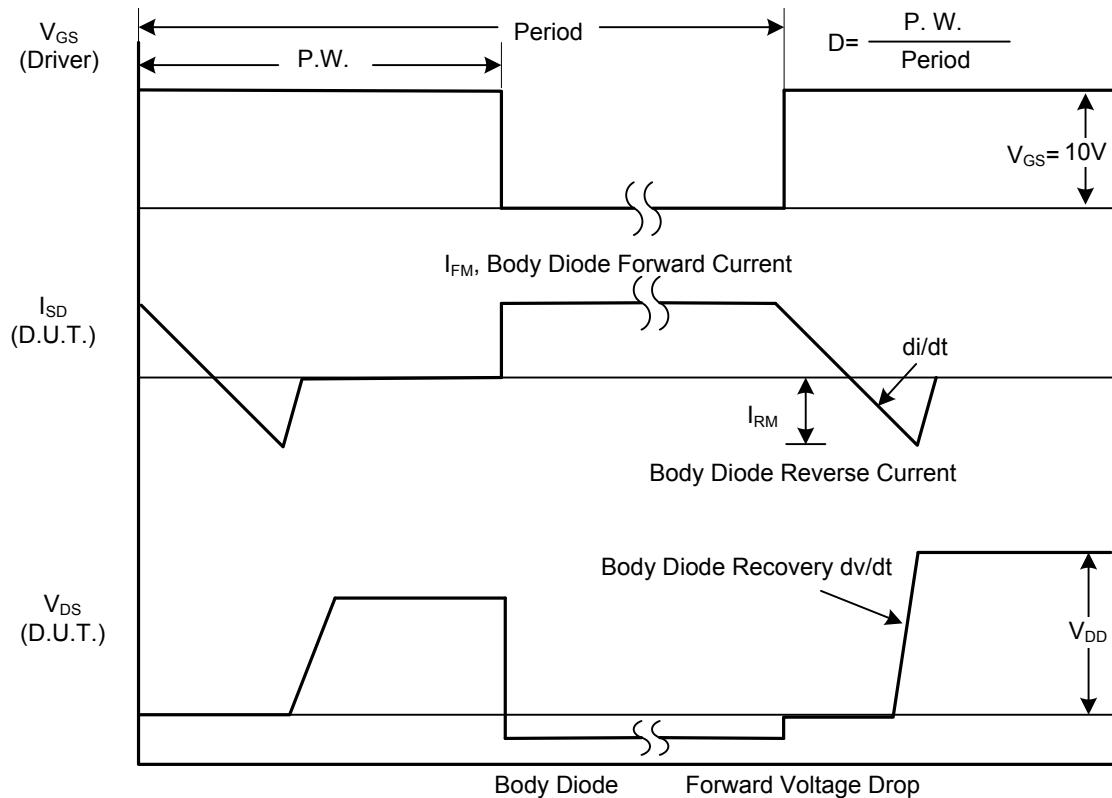
Note: 1. Pulse Test: Pulse width  $\leq 250\mu s$ , Duty cycle  $\leq 2\%$

2. Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS

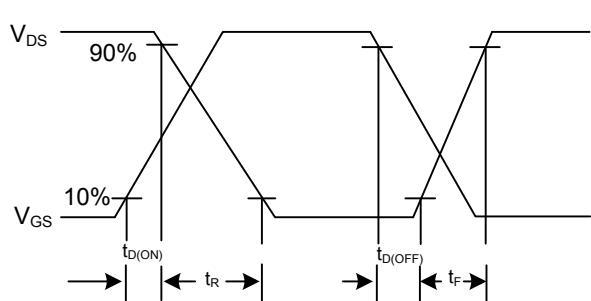
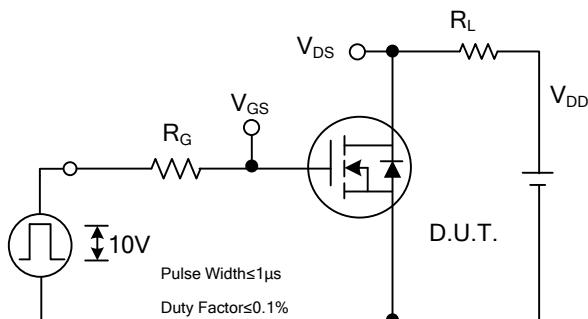


**Peak Diode Recovery dv/dt Test Circuit**



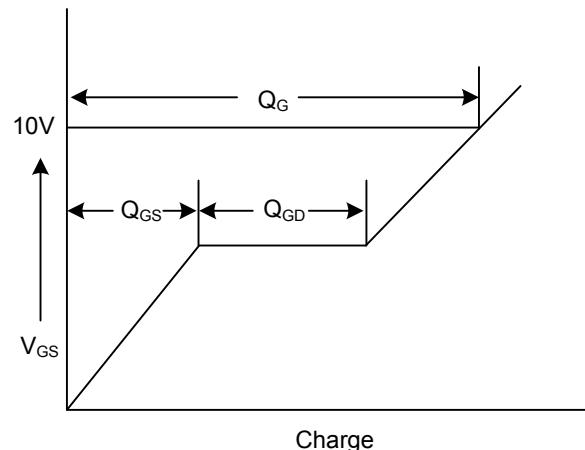
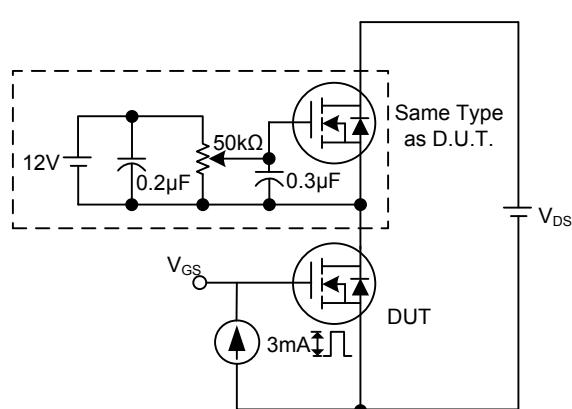
**Peak Diode Recovery dv/dt Waveforms**

■ TEST CIRCUITS AND WAVEFORMS (Cont.)



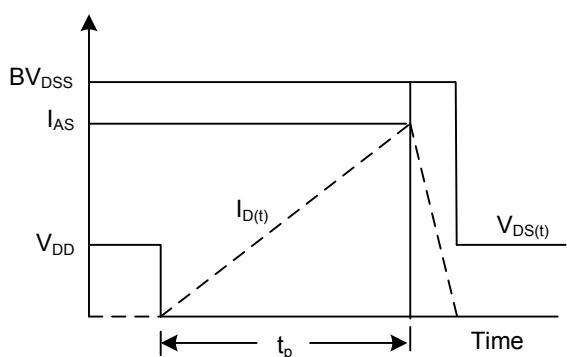
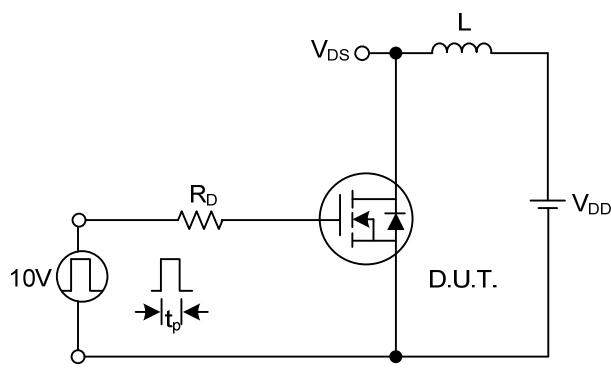
Switching Test Circuit

Switching Waveforms



Gate Charge Test Circuit

Gate Charge Waveform

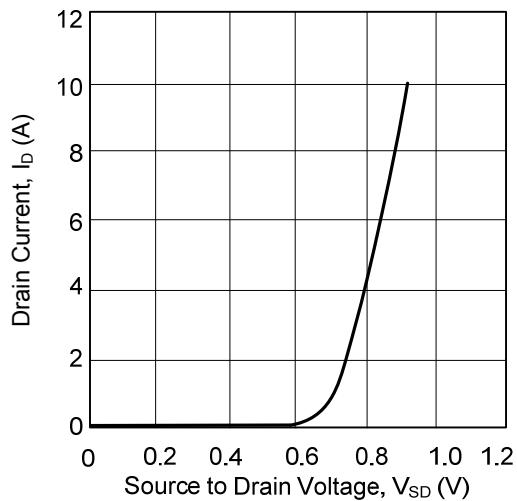


Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

- TYPICAL CHARACTERISTICS

Drain Current vs. Source to Drain Voltage



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